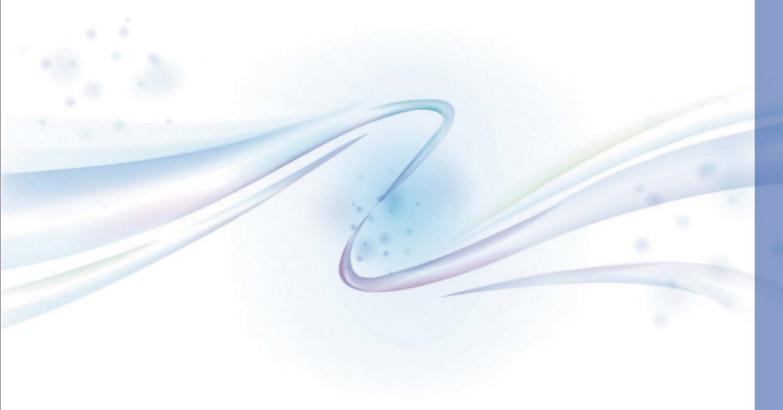
## Build Together, Change Tomorrow.

# **DONGHO A-TEC**







#### Dong Ho A-Tec

takes pride in understanding our customers' businesses, providing ultra-precision molds such as semiconductor mold and injection mold, and manufacturing products of stamping and injection which give our customers a strategic advantage.

From product and mold design to provide the competitiveness, Dong Ho A-Tec develops ultra-precision molds which provide the most effective and efficient production solutions in the industry.

Through technical innovation as well as high performance facilities along with equipment based on nearly 30- year business career, Dong Ho A-Tec differentiates itself by delivering value to the global business partners.

With the vision of a global hidden champion offering leading edge ultra-precision technology, resources and experience, we strive to drive developments, tackling challenges and deepening relationship with our business partners around the world.



Choi, Wong Hak, CEO

## Certificates



















#### Company Summary

Dong Ho A-Tec Co.,Ltd Company Name

Established 25th April 1994

Address 82, Hwajeonsandan 3-ro (Hwajeon-dong), Gangseo-gu,

Busan, Korea

 Certificates ISO 9001:2015 Certification, IATF 16949 Certification

Major Mold Products IC, LED & Power TR Lead Frame Die Set

Down Set Die Set / LOC, BGA Tapping Die Set

Mold Product Type IC:SOIC/TSOP/TSSOP/PLCC/QFP/LQFP

TR:To-220 / TO-247 / TO-252 / TO-3P / FULL-PAK

Products: Leadframe Press Production, Manufacturing Injection Products

(Electronics, defence products, Etc)

Malaysia Overseas Factory

06 Changed to Dongho A-Tec

05 Obtained system certification of ISO 9002

Established Dongho Precision Co. Ltd.

09 Be recognized as a R&D institute of mold design

Received the award of the export tower of one million dollar

national industry.

1999

1998

1994

05







2019	11	Received Industrial Peace Prize (Busan Mayor's Award)
2018	01	Was chosen for a "Root Company" which provides essential root technologies like the root of a tree
	12	Obtained system certification of IATF 16949
	12	Obtained system certification of ISO 9001 2015
2014	02	Be re-recognized as a R & D institute
2010	05	Obtained system certification of ISO 9001 2008
	06	Be designated as a promising small and medium-sized export company
	10	Moved to a new larger construction located in Hwajeondong, Gangseo-gu, Busan
2009	05	Won a prize at the first Busan small and medium-sized business contest
2008	04	Singed the MOU on industry university cooperation between Dongho A-Tec and Kyungnam College of Information & Technology
2006	12	Be chosen for a leading company in the machinery parts and materials industry of Busan
2003	10	Receive patent certification for automatic design method of semiconductor leadframe
2002	07	Be selected as INNO BIZ company
2001	01	Be designated as a leading vision 21company
	06	Established a Malaysian local corporation
	11	Received the award of the export tower of 5 million dollars and the Prime Minister's Award
2000	02	Was selected as a company with outstanding performance in the technological competitiveness

Received President's Award for the contribution to the development of the





Our R & D aims at providing the very highest quality products by listening to our customers. In order to stabilize our products and realize the top level of ultra-precision, we are committed to continuous research and development as well as quality improvement.

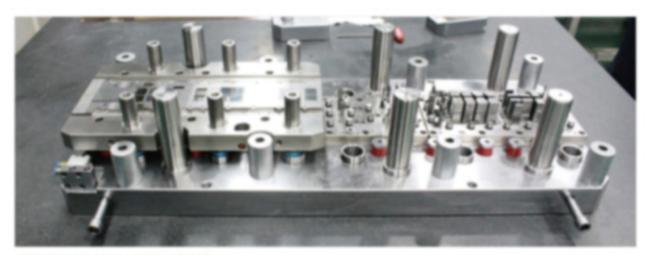
We will continue to strive to provide fast and accurate design, competitive pricing, the shortest lead time, and top-quality products by implementing the optimized design standards as much as possible.

Program (Government Enforcement Agency)	Project	Development Period	Project Cost	Status
Technology Development for Innovative Companies (Ministry of Small and Medium Enterprises)	Mold Development for Thin Thickness and Wide Width of Semiconductor Leadframe	Two Years	676	Ongoing
Industry University Joint Technology Development Program(Ministry of Small and Medium Enterprises)	Mold Development's for Semiconductor Leadframe Using Ultra-precise Integral Die	One year	100	Succeeded
Innovation Development Program for : Small and Medium-Sized Business (Ministry of Small and Medium Enterprises)	Development of Stamping Tool for Mass Production of 144 Pins Leadframe	One year	108	Succeeded
Innovation Development Program for Small and Medium-Sized Business (Ministry of Trade, Industry and Energy)	Development of Stamping Tool for Semiconductor Leadframe with 130mm Wide Width	One year	124	Succeeded
Industrial Technology Development Program(Ministry of Trade, Industry and Energy)	Development of Stamping Tool for Next-Generation BGA Semiconductor	One year	297	Succeeded
Innovation Development Program for: Small and Medium-Sized Business (Ministry of Small and Medium Enterprises)	System Development for Design Automation of Semiconductor Leadframe	One year	472	Succeeded



#### Semiconductor Mold & Leadframe

Semiconductor Mold, L/F Die

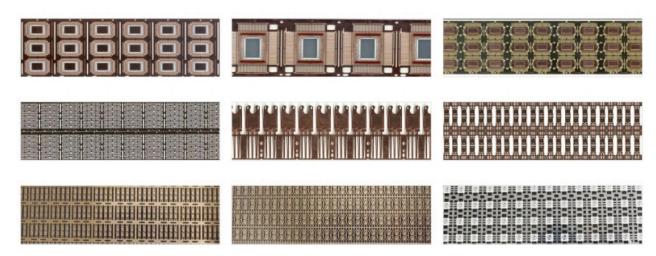


IC, LED & Power TR Lead Frame Die Set Down set Die Set / LOC,  $\mu$  BGA Tapping Die Set





#### Leadframe



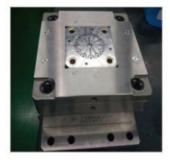
## Injection Mold & Product

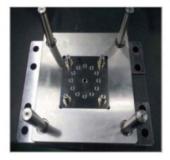
#### Injection Molds





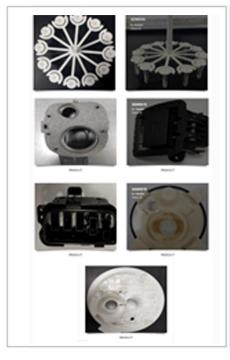






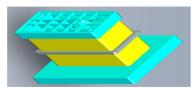


#### Injection Products













#### Leadframe Manufacturing Process(Semiconductor/LED)

#### Mold Making







Milling/Machining



Tungsten Cemented Carbide Grinding



Steal Grinding



Jig Grinding



EDM:Wire EDM



**Profile Grinding** 



Large Scale Grinding



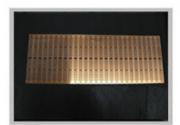
Parts Inspection



Assembly

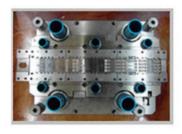


TO(Try Out)



Product Inspection

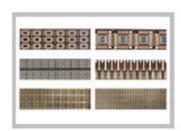
#### Press Production



Mold Making (Mold Taking Over)



Pressing



Pressed Product



Inspection/Delivery

## Injection Mold Manufacturing Process









Mold Making (Mold Taking Over)

Injection Work

Injection product

Inspection/Delivery



#### Production Equipment

#### **Press**





## Injection





## Equipment







© DONGHO A-TEC CO., LTD.

Machining





© DONGHO A-TEC CO., LTD.

Tungsten Cemented Carbide Grinding





© DONGHO A-TEC CO., LTD.

Steal Grinding





© DONGHO ATEC CO., LTD.

Large Scale Grinding





Profile Grinding





© DONGHO A-TEC CO., LTD.
Wire EDM





























Equipment List			
MACHINE CENTER	5	SURFACE GRINDER	3
CNC /JIG GRINDING	4	BLOHM PLANOMAT 612	1
CNC WIRE CUT E.D.M (Oil type 6)	14	CNC E.D.M / E.D.M	4
STAMPING PRESS	8	INJECTION MOLDING MACHINE	8
CHART MAKING CAD SYSTEM	1	NEXIV, Mitutoyo (3차원 측정기)	2
CNC OPTICAL PROFILE GRINDER	5	HARDNESS TESTER	2
FORMING SURFACE GRINDER	20	OPTICAL PROJECTOR	5
SUPER E.D.M DRILL	3	TOOL MICROSCOPE	2
MILLING	4	CAD SYSTEM	9
SUPER E.D.M DRILL	3	TOOL MICROSCOPE	2
MILLING	4	CAD SYSTEM	9





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